

Customer No.: 31561  
Docket No.: 12234-US-PA  
Application No.: 10/711,281

### REMARKS

#### Present Status of the Application

Claims 1, 2 and 6 are objected to because of informalities. Claims 5 and 6 are rejected under 35 U.S.C. 112, 2<sup>nd</sup> paragraph as being indefinite. Claims 1-4 and 6 are also rejected under 35 U.S.C. 102(e) as being anticipated by Cheng et al..

#### Discussion of Office Action

Applicant has amended claims 1,2,4,5,6 more clearly. In response thereto, sufficient antecedent basis for **"the farthest bonding pads"** in the amended claim 4 for supporting claim 5, and the limitation **"a part of the Nth layer"** in the amended claim 6 are both allowable to meet the second paragraph of 35 U.S.C. 112.

In addition, based on the objection for claims 1 and 2, Applicant has amended "close to the device area" to **"closest to the device area and the bonding pads next to the closest bonding pads"**, which comprise the first bonding pad row R1 and the second bonding pad row R2 for signal in Fig.4. As to the meanings of "overstride" and "overlape", applicant would rather use "overstride" than "overlape" due to better understanding. US patent NO. 7,113,060 in abstract, citing as applicant likes that "the conductor layer (2) as the ground and the conductor layer (2b) as a signal conductor is configured so as to *overstride* the inductive windows configured by the via-holes (3a)".

Moreover, applicant respectfully requests considering claim 1 is distinguished from the Cheng et al set forth as the following reasons:

**The Cheng et al does not provides a fact that the "conductive layer M5" is the**

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**circuit layer farthest from the substrate defined in the claim 1.**

In the Office Action at the page 3, Examiner explained that "the circuit layer farthest M5 from the substrate has a plurality of bonding pads (22,24,M6 in figure 5b)". However, Examiner just considers that conductive layer M6 is likely the bonding pad rather than the circuit layer farthest from the substrate, but applicant consider it is not reasonable. The real bonding pads as Cheng disclosed in the specification are S1, S2, P1 and P2 (in Fig.5a), which disposed on the above of the conductive layer M6 and not located on a same layer with the conductive layer M6. In addition, the bonding pads S1 and S2 connect to the lower conductive layer M5 through the vias rather than connecting to the conductive layer M6.

To make the original claim 1 clearer to show that the signal line L6 connected to the bonding pad 231 enters the device area B2 and runs on the topmost circuit layer M6, so that the signal line L6 overstrides the power ring 240 and the ground ring 250 to prevent from alternating with the power line or ground line. Applicant amended the claim 1. base on the above, claim 1 is also characterized by "the bonding pads and the signal lines are located at a same layer, and the signal lines overstride at least a power/ground ring of the circuit layers within the device area, the bonding pads closest to the device area and the bonding pads next to the closest to the device area connect to the signal lines respectively, and then electrically connect with the circuit layer closer to the substrate through the vias, which passing through the power/ground ring".

However, it is not disclosed in the reference that the bonding pads S1, S2, P1, G1 and conductive layer M6 are at a same layer, either the signal line overstrides the

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power/ground ring and the via passes through the power/ground ring. It is believed that claim 1, distinguished from the reference in the Office Action, should be considered as meeting the novelty requirement.

Therefore, Applicant respectfully request considering the rejections of claims 1-4 and 6 should be withdrawn.

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**CONCLUSION**

For at least the foregoing reasons, it is believed that the pending claims 1-9 are in proper condition for allowance and an action to such effect is earnestly solicited. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

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Respectfully submitted,

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